

## SMD2018 Series

#### Features

- Surface Mount Devices
- Lead free device ■ Size 5.0\*4.5mm/0.20\*0.18 inch
- Surface Mount packaging for automated assembly

#### Applications

Almost anywhere there is a low voltage power supply, up to 60V and a load to be protected, including:

■ Computer mother board, Modem.

■ Telecommunication equipments.

Alpha-Top (Sea & Land Alliance)

## **Performance Specification**

$V_{max}$ $I_{max}$		I <sub>hold</sub>	l <sub>trip</sub>	$P_d$	Maximum Time To Trip		Resistance		Agency Approval	
	(A)	@25°C (A)	@25°C (A)	Typ. (W)			Ri <sub>min</sub> (Ω)	$R1_{max}$ ( $\Omega$ )	UL	TUV
60	100	0.30	0.60	0.9	1.5	3.00	0.500	2.300		
60	100	0.55	1.20	1.0	2.5	3.00	0.200	1.000		
15	100	1.10	2.20	1.1	8.0	0.40	0.060	0.360		
24	100	1.10	2.20	1.1	8.0	0.40	0.060	0.360		
33	100	1.10	2.20	1.1	8.0	0.40	0.060	0.360		
15	100	1.50	3.00	1.1	8.0	0.80	0.050	0.170		
10	100	2.00	4.00	1.1	8.0	2.40	0.030	0.100		
	60 15 24 33 15	(Vdc)         (A)           60         100           60         100           15         100           24         100           33         100           15         100           10         100	(Vdc) (A) (A) 60 100 0.30 60 100 0.55 15 100 1.10 24 100 1.10 33 100 1.10 15 100 1.50 10 100 2.00	(Vdc)         (A)         (A)         (A)           60         100         0.30         0.60           60         100         0.55         1.20           15         100         1.10         2.20           24         100         1.10         2.20           33         100         1.10         2.20           15         100         1.50         3.00           10         100         2.00         4.00	(Vdc)         (A)         (A)         (A)         (W)           60         100         0.30         0.60         0.9           60         100         0.55         1.20         1.0           15         100         1.10         2.20         1.1           24         100         1.10         2.20         1.1           33         100         1.10         2.20         1.1           15         100         1.50         3.00         1.1           10         100         2.00         4.00         1.1	V <sub>max</sub> I <sub>max</sub> I <sub>hold</sub> @25°C         I <sub>trib</sub> @25°C         P <sub>d</sub> Time Tourrent           (Vdc)         (A)         (A)         (A)         (W)         Current           60         100         0.30         0.60         0.9         1.5           60         100         0.55         1.20         1.0         2.5           15         100         1.10         2.20         1.1         8.0           24         100         1.10         2.20         1.1         8.0           33         100         1.10         2.20         1.1         8.0           15         100         1.50         3.00         1.1         8.0           10         100         2.00         4.00         1.1         8.0	V <sub>max</sub> I <sub>max</sub> I <sub>hold</sub> @25°C         I <sub>trin</sub> @25°C         P <sub>d</sub> Typ. Current         Time To Trip Current           (Vdc)         (A)         (A)         (A)         (W)         (A)         (Sec)           60         100         0.30         0.60         0.9         1.5         3.00           60         100         0.55         1.20         1.0         2.5         3.00           15         100         1.10         2.20         1.1         8.0         0.40           24         100         1.10         2.20         1.1         8.0         0.40           33         100         1.10         2.20         1.1         8.0         0.40           15         100         1.50         3.00         1.1         8.0         0.80           10         100         2.00         4.00         1.1         8.0         2.40	V <sub>max</sub> I <sub>max</sub> I <sub>hold</sub> @25°C         e25°C         Typ.         Current Current Time (Sec)         Ri <sub>min</sub> (Qurrent Time (Sec)         Qurrent Time (Sec)         Ri <sub>min</sub> (Qurrent Time (Sec)         Qurrent Ti	V <sub>max</sub> I <sub>max</sub> I <sub>hold</sub> @25°C         U <sub>trin</sub> @25°C         P <sub>d</sub> Typ. Current         Time To Trip Time To Trip Current         Ri <sub>min</sub> R1 <sub>max</sub> R1 <sub>max</sub> (Ω)           (Vdc)         (A)         (A)         (A)         (W)         (A)         (Sec)         (Ω)         (Ω)           60         100         0.30         0.60         0.9         1.5         3.00         0.500         2.300           60         100         0.55         1.20         1.0         2.5         3.00         0.200         1.000           15         100         1.10         2.20         1.1         8.0         0.40         0.060         0.360           24         100         1.10         2.20         1.1         8.0         0.40         0.060         0.360           33         100         1.10         2.20         1.1         8.0         0.40         0.060         0.360           15         100         1.50         3.00         1.1         8.0         0.80         0.050         0.170           10         100         2.00         4.00         1.1         8.0         2.40         0.030         0.100	V <sub>max</sub> I <sub>max</sub> I <sub>hold</sub> @25°C @25°C @25°C Typ.         P <sub>d</sub> Vurrent Time (M)         Ri <sub>min</sub> R1 <sub>max</sub> (M)         RI <sub>min</sub> R1 <sub>max</sub> (M)         UL           (Vdc)         (A)         (A)         (A)         (W)         (A)         (Sec)         (Ω)         (Ω)         (Ω)           60         100         0.30         0.60         0.9         1.5         3.00         0.500         2.300         0.60         0.9         1.5         3.00         0.200         1.000         1.000         1.000         0.200         1.000         0.200         1.000         0.200         1.000         0.200         1.000         0.360         0.24         100         1.10         2.20         1.1         8.0         0.40         0.060         0.360         0.360         0.360         0.360         0.360         0.360         0.360         0.360         0.360         0.050         0.170         0.000         0.070

**Ihold** = Hold Current. Maximum current device will not trip in 25°C still air.

**Itrip** = Trip Current. Minimum current at which the device will always trip in 25°C still air.

Vmax = Maximum operating voltage device can withstand without damage at rated current (Imax).

**Imax** = Maximum fault current device can withstand without damage at rated voltage (Vmax).

Pd = Power dissipation when device is in the tripped state in 25°C still air environment at rated voltage.

Rimin/max = Minimum/Maximum device resistance prior to tripping at 25°C.

 $R1_{max}$  = Maximum device resistance is measured one hour post reflow.

CAUTION: Operation beyond the specified ratings may result in damage and possible arcing and flame.

#### **Environmental Specifications**

Test	Conditions				
Passive aging	+85°C, 1000 hrs.				
Humidity aging	+85°C, 85% R.H., 168 hours				
Thermal shock	+85°C to -40°C, 20 times				
Resistance to solvent	MIL-STD-202,Method 215				
Vibration	MIL-STD-202,Method 201				
Ambient operating conditions : - 40 °C to +85 °C					
Maximum surface temperature of the device in the tripped state is 125 °C					

Agency Approvals : UL pending

Regulation/Standard: PS RoHS 2011/65/EU

**1F** EN14582

#### I<sub>hold</sub> Versus Temperature

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Model	Maximum ambient operating temperature (T <sub>mao</sub> ) vs. hold current (I <sub>hold</sub> )									
Model	-40°C	-20°C	0°C	25°C	40°C	50°C	60°C	70°C	85°C	
SMD2018-030	0.48	0.42	0.35	0.30	0.24	0.21	0.17	0.15	0.10	
SMD2018-050	0.87	0.77	0.67	0.55	0.46	0.41	0.36	0.31	0.23	
SMD2018-100	1.71	1.52	1.32	1.10	0.94	0.84	0.74	0.64	0.50	
SMD2018-150	2.38	2.10	1.82	1.50	1.27	1.13	0.99	0.85	0.64	
SMD2018-200	2.95	2.65	2.35	2.00	1.74	1.59	1.44	1.29	1.06	

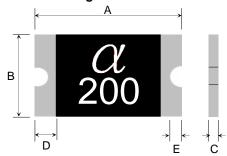


## SMD2018 Series

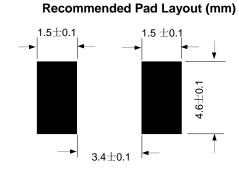
Construction And Dimension (Unit:mm)

Model	Α		В		С		D	E
Model	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Min.
SMD2018-030	4.72	5.44	4.22	4.93	0.60	1.10	0.30	0.30
SMD2018-050	4.72	5.44	4.22	4.93	0.70	1.30	0.30	0.30
SMD2018-100	4.72	5.44	4.22	4.93	0.45	0.80	0.30	0.30
SMD2018-100-24V	4.72	5.44	4.22	4.93	0.60	1.30	0.30	0.30
SMD2018-100-33V	4.72	5.44	4.22	4.93	0.60	1.30	0.30	0.30
SMD2018-150	4.72	5.44	4.22	4.93	0.45	0.80	0.30	0.30
SMD2018-200	4.72	5.44	4.22	4.93	0.40	0.80	0.30	0.30

#### **Dimensions & Marking**



C = Trademark 200 = Hold current



#### **Termination Pad Characteristics**

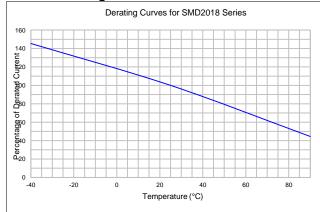
Gold-Plated Nickel-Copper or Tin-plated Nickel-Copper Terminal pad materials:

Meets EIA specification RS186-9E and ANSI/J-STD-002 Category 3. Terminal pad solderability:

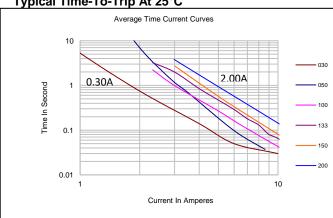
Rework

Use standard industry practices, the removal device must be replaced with a fresh one.

## **Thermal Derating Curve**



## Typical Time-To-Trip At 25°C



# WARNING:

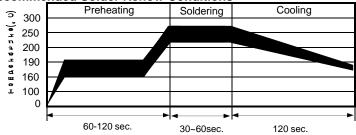
- · Use PPTC beyond the maximum ratings or improper use may result in device damage and possible electrical arcing and flame.
- PPTC are intended for protection against occasional over current or over temperature fault conditions and should not be use d when repeated fault conditions or prolonged trip events are anticipated.
- Device performance can be impacted negatively if devices are handled in a manner inconsistent with recommended electronic, thermal, and mechanical procedures for electronic components.

- Use PPTC with a large inductance in circuit will generate a circuit voltage (L di/dt) above the rated voltage of the PPTC.
  Avoid impact PPTC device its thermal expansion like placed under pressure or installed in limited space.
  Contamination of the PPTC material with certain silicon based oils or some aggressive solvents can adversely impact the per formance of the devices. PPTC SMD can be cleaned by standard methods.
- Requests that customers comply with our recommended solder pad layouts and recommended reflow profile. Improper board layou ts or reflow profile could negatively impact solderability performance of our devices.



## SMD2018 Series

**Recommended Solder Reflow Conditions** 



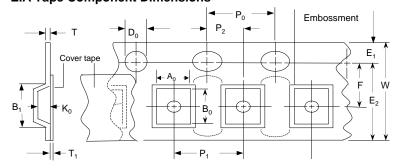
- Recommended reflow methods: IR, vapor phase oven, hot air oven.
- Devices are not designed to be wave soldered to the bottom side of the board.
- Recommended maximum paste thickness is 0.25 mm (0.010 inch).
- Devices can be cleaned using standard method and solvents.

  Note: If reflow temperatures exceed the recommended profile,
  - devices may not meet the performance requirements.

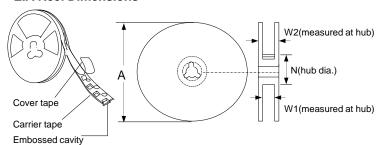
#### Tape And Reel Specifications (mm)

<b>Governing Specification</b>	s EIA 481-2
W	12.0 ± 0.20
$P_0$	4.0 ± 0.10
P <sub>1</sub>	8.0 ± 0.10
P <sub>2</sub>	$2.0 \pm 0.05$
A <sub>0</sub>	$4.40 \pm 0.10$
B <sub>0</sub>	5.50 ± 0.10
B₁max.	8.2
D <sub>0</sub>	1.5 + 0.1, -0.0
F	5.5 ± 0.05
E <sub>1</sub>	1.75 ± 0.10
E <sub>2</sub> min.	10.25
Tmax.	0.6
T₁max.	0.1
K <sub>0</sub>	1.36 ± 0.1
Leader min.	390
Trailer min.	160
Reel Dimensions	
A max.	178
N min.	50
W <sub>1</sub>	12.4 + 2.0, -0.0
W₂max.	18.4

## **EIA Tape Component Dimensions**



#### **EIA Reel Dimensions**



## **Storage And Handling**

- Storage conditions: 40°C max, 70% R.H.
- Devices may not meet specified performance if storage conditions are exceeded.

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### Order Information Packaging

SMD2018	050	Tape & Reel Quantity
Product name	Hold	030, 050,100-24V, 100-33V : 1,500 pcs/reel
Size 5045mm/2018 inch	Current	100, 150, 200 : 2,500 pcs/reel
SMD: surface mount device	0.50A	

Devices taped with reference to EIA481 standard.